

SKM 145GB123D



SEMITRANS[®] 2

IGBT Modules

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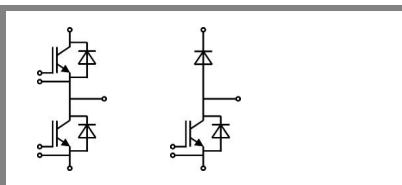
SKM 145GAL123D

Features

- MOS input (voltage controlled)
- N channel, Homogeneous Si
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to $6 \times I_{Cnom}$
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (10 mm) and creepage distances (20 mm)

Typical Applications

- Switching (not for linear use)
- AC inverter drives



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Absolute Maximum Ratings		$T_c = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$	1200		V
I_C	$T_j = 150^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	145	A
		$T_{case} = 80^\circ\text{C}$	110	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	200		A
V_{GES}		± 20		V
t_{psc}	$V_{CC} = 600\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 125^\circ\text{C}$ $V_{CES} < 1200\text{ V}$	10		μs

Inverse Diode				
I_F	$T_j = 150^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	130	A
		$T_{case} = 80^\circ\text{C}$	90	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	200		A
I_{FSM}	$t_p = 10\text{ ms}; \text{sin.}$	$T_j = 150^\circ\text{C}$	900	

Freewheeling Diode				
I_F	$T_j = 150^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	170	A
		$T_{case} = 80^\circ\text{C}$	115	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	300		A
I_{FSM}	$t_p = 10\text{ ms}; \text{sin.}$	$T_j = 150^\circ\text{C}$	1440	

Module				
$I_{t(RMS)}$		200		A
T_{vj}		- 40 ... + 150		$^\circ\text{C}$
T_{stg}		- 40 ... + 125		$^\circ\text{C}$
V_{isol}	AC, 1 min.	2500		V

Characteristics		$T_c = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 4\text{ mA}$	4,5	5,5	6,5	V
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$	$T_j = 25^\circ\text{C}$		0,1	0,3
V_{CE0}		$T_j = 25^\circ\text{C}$		1,4	1,6
		$T_j = 125^\circ\text{C}$		1,6	1,8
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$		11	14
		$T_j = 125^\circ\text{C}$		15	19
$V_{CE(sat)}$	$I_{Cnom} = 100\text{ A}, V_{GE} = 15\text{ V}$	$T_j = ^\circ\text{C}_{chiplev.}$		2,5	3
C_{ies}	$V_{CE} = 25, V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		6,5	8,5
C_{oes}				1	1,5
C_{res}				0,5	0,6
Q_G	$V_{GE} = -8\text{ V} - +20\text{ V}$			1000	nC
R_{Gint}	$T_j = ^\circ\text{C}$			5	Ω
$t_{d(on)}$	$R_{Gon} = 6,8\ \Omega$	$V_{CC} = 600\text{ V}$	$I_C = 100\text{ A}$	160	320
t_r				80	160
E_{on}				16	
$t_{d(off)}$	$R_{Goff} = 6,8\ \Omega$	$T_j = 125^\circ\text{C}$	$V_{GE} = -15\text{ V}$	400	520
t_f				70	100
E_{off}				12	
$R_{th(j-c)}$	per IGBT			0,15	K/W

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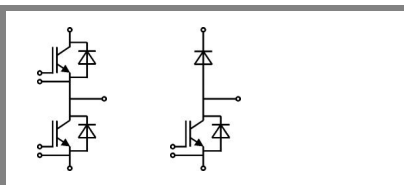
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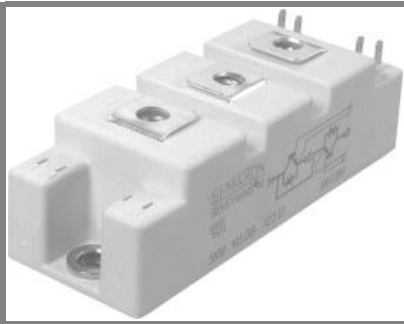
Characteristics

Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 100 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$	2	2,5	V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$	1,8		V
V_{F0}		$T_j = 25 \text{ }^\circ\text{C}$	1,1	1,4	V
		$T_j = 125 \text{ }^\circ\text{C}$			V
r_F		$T_j = 25 \text{ }^\circ\text{C}$	9	11	mΩ
		$T_j = 125 \text{ }^\circ\text{C}$			mΩ
I_{RRM}	$I_F = 100 \text{ A}$	$T_j = 25 \text{ }^\circ\text{C}$	35		A
Q_{rr}	$di/dt = 1000 \text{ A}/\mu\text{s}$		5		μC
E_{rr}	$V_{GE} = 0 \text{ V}; V_{CC} = 600 \text{ V}$				mJ
$R_{th(j-c)D}$	per diode			0,36	K/W
Freewheeling Diode					
$V_F = V_{EC}$	$I_{Fnom} = 150 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$	2	2,5	V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$	1,8		V
V_{F0}		$T_j = 25 \text{ }^\circ\text{C}$	1,1	1,4	V
		$T_j = 125 \text{ }^\circ\text{C}$			V
r_F		$T_j = 25 \text{ }^\circ\text{C}$	9	11	V
		$T_j = 125 \text{ }^\circ\text{C}$			V
I_{RRM}	$I_F = 150 \text{ A}$	$T_j = 25 \text{ }^\circ\text{C}$	55		A
Q_{rr}			8		μC
E_{rr}	$V_{GE} = 0 \text{ V}; V_{CC} = 600 \text{ V}$				mJ
$R_{th(j-c)FD}$	per diode			0,3	K/W
Module					
L_{CE}				30	nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25 \text{ }^\circ\text{C}$	0,75		mΩ
		$T_{case} = 125 \text{ }^\circ\text{C}$	1		mΩ
$R_{th(c-s)}$	per module			0,05	K/W
M_s	to heat sink M6		3	5	Nm
M_t	to terminals M5		2,5	5	Nm
w				160	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

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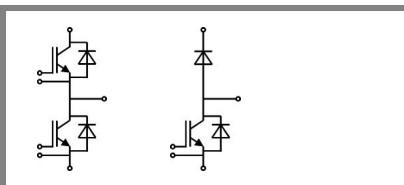
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Z_{th}		Values	Units
Symbol	Conditions		
$Z_{th(j-c)I}$			
R_{θ}	$i = 1$	100	mk/W
R_{θ}	$i = 2$	38	mk/W
R_{θ}	$i = 3$	10	mk/W
R_{θ}	$i = 4$	2	mk/W
τ_{θ}	$i = 1$	0,03	s
τ_{θ}	$i = 2$	0,0287	s
τ_{θ}	$i = 3$	0,0012	s
τ_{θ}	$i = 4$	0,0002	s
$Z_{th(j-c)D}$			
R_{θ}	$i = 1$	240	mk/W
R_{θ}	$i = 2$	95	mk/W
R_{θ}	$i = 3$	22	mk/W
R_{θ}	$i = 4$	3	mk/W
τ_{θ}	$i = 1$	0,054	s
τ_{θ}	$i = 2$	0,0113	s
τ_{θ}	$i = 3$	0,0012	s
τ_{θ}	$i = 4$	0,005	s



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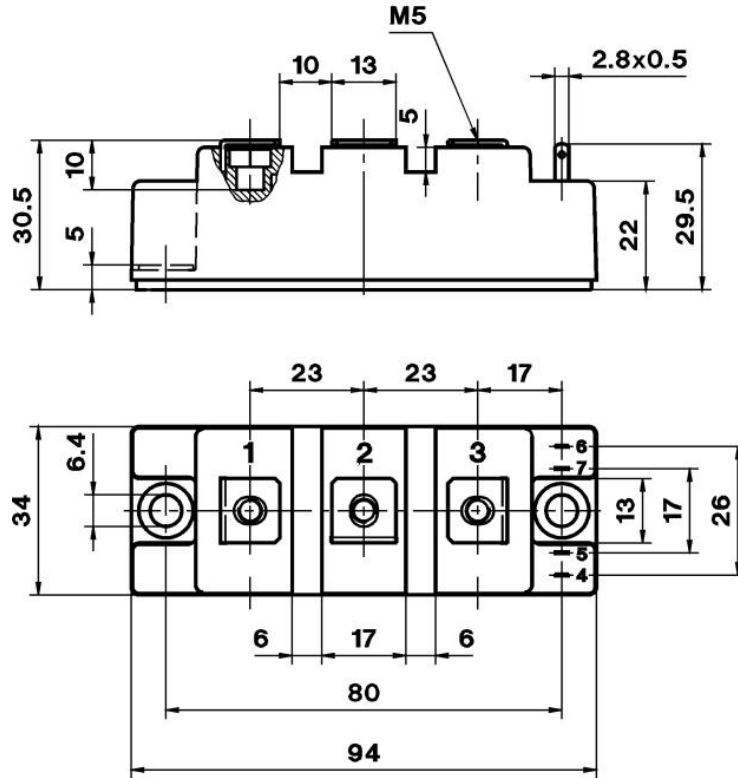
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UL Recognized

CASED61

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Case D 61

